

Maximum Ratings – N-CHANNEL, Q1 @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	35	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 4) V _{GS} = 10V	Steady State	T _A = 25°C	I _D	5.3	A
		T _A = 70°C		4.2	
Continuous Drain Current (Note 5) V _{GS} = 10V	Steady State	T _A = 25°C	I _D	8.6	A
		T _A = 70°C		6.8	
Continuous Drain Current (Note 5) V _{GS} = 10V	t ≤ 10s	T _A = 25°C	I _D	13	A
		T _A = 70°C		11	
Continuous Drain Current (Note 5) V _{GS} = 4.5V	Steady State	T _A = 25°C	I _D	6.3	A
		T _A = 70°C		5.0	
Continuous Drain Current (Note 5) V _{GS} = 4.5V	t ≤ 10s	T _A = 25°C	I _D	9.3	A
		T _A = 70°C		7.4	
Pulsed Drain Current (Note 6)			I _{DM}	50	A

Maximum Ratings – P-CHANNEL, Q2 @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-35	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 4) V _{GS} = -10V	Steady State	T _A = 25°C	I _D	-5.0	A
		T _A = 70°C		-3.8	
Continuous Drain Current (Note 5) V _{GS} = -10V	Steady State	T _A = 25°C	I _D	-7.8	A
		T _A = 70°C		-6.2	
Continuous Drain Current (Note 5) V _{GS} = -10V	t ≤ 10s	T _A = 25°C	I _D	-12	A
		T _A = 70°C		-10	
Continuous Drain Current (Note 5) V _{GS} = -4.5V	Steady State	T _A = 25°C	I _D	-6.5	A
		T _A = 70°C		-5.2	
Continuous Drain Current (Note 5) V _{GS} = -4.5V	t ≤ 10s	T _A = 25°C	I _D	-9.6	A
		T _A = 70°C		-7.7	
Pulsed Drain Current (Note 6)			I _{DM}	-50	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P _D	1.54	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 4)	R _{θJA}	81.3	°C/W
Power Dissipation (Note 5)	P _D	4.1	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 5)	R _{θJA}	30.8	°C/W
Power Dissipation (Note 5) t ≤ 10s	P _D	8.9	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 5) t ≤ 10s	R _{θJA}	14	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
 - Device mounted on 2" x 2" FR-4 PCB with high coverage 2 oz. Copper, single sided.
 - Repetitive rating, pulse width limited by junction temperature.

Electrical Characteristics – N-CHANNEL, Q1 @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	35	-	-	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	1.0	μA	V _{DS} = 35V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	1.0	-	3.0	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	-	25	35	mΩ	V _{GS} = 10V, I _D = 8A
			50	65		V _{GS} = 4.5V, I _D = 6A
Forward Transfer Admittance	Y _{fs}	-	4.5	-	S	V _{DS} = 10V, I _D = 8A
Diode Forward Voltage	V _{SD}	-	-	1.2	V	V _{GS} = 0V, I _S = 8A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	-	850	-	pF	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	64.7	-	pF	
Reverse Transfer Capacitance	C _{rss}	-	51.9	-	pF	
Gate Resistance	R _g	-	1.6	-	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 10V)	Q _g	-	18.7	-	nC	V _{GS} = 10V, V _{DS} = 28V, I _D = 8A
Total Gate Charge (V _{GS} = 4.5V)	Q _g	-	8.8	-		V _{GS} = 4.5V, V _{DS} = 28V, I _D = 8A
Gate-Source Charge	Q _{gs}	-	2.6	-		
Gate-Drain Charge	Q _{gd}	-	2.1	-		
Turn-On Delay Time	t _{D(on)}	-	5.4	-	ns	V _{DS} = 18V, V _{GS} = 10V, R _L = 18Ω, R _G = 3.3Ω, I _D = 1A
Turn-On Rise Time	t _r	-	2.8	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	33.2	-	ns	
Turn-Off Fall Time	t _f	-	35.6	-	ns	

Electrical Characteristics – P-CHANNEL, Q2 @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-35	-	-	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	-1.0	μA	V _{DS} = -35V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	-1.0	-	-3.0	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(on)}	-	30	45	mΩ	V _{GS} = -10V, I _D = -6A
			40	65		V _{GS} = -4.5V, I _D = -4A
Forward Transfer Admittance	Y _{fs}	-	8	-	S	V _{DS} = -10V, I _D = -6A
Diode Forward Voltage	V _{SD}	-	-	-1.2	V	V _{GS} = 0V, I _S = -6A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	-	985.2	-	pF	V _{DS} = -25V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	90.6	-	pF	
Reverse Transfer Capacitance	C _{rss}	-	75.3	-	pF	
Gate Resistance	R _g	-	7.0	-	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = -10V)	Q _g	-	19.2	-	nC	V _{GS} = -10V, V _{DS} = -28V, I _D = -6A
Total Gate Charge (V _{GS} = -4.5V)	Q _g	-	9.5	-		V _{GS} = -4.5V, V _{DS} = -28V, I _D = -6A
Gate-Source Charge	Q _{gs}	-	2.0	-		
Gate-Drain Charge	Q _{gd}	-	3.5	-		
Turn-On Delay Time	t _{D(on)}	-	5.2	-	ns	V _{DS} = -18V, V _{GS} = -10V, R _L = 18Ω, R _G = 3.3Ω, I _D = -1A
Turn-On Rise Time	t _r	-	4.8	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	45.8	-	ns	
Turn-Off Fall Time	t _f	-	29.5	-	ns	

Notes: 7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to production testing.

N-CHANNEL, Q1

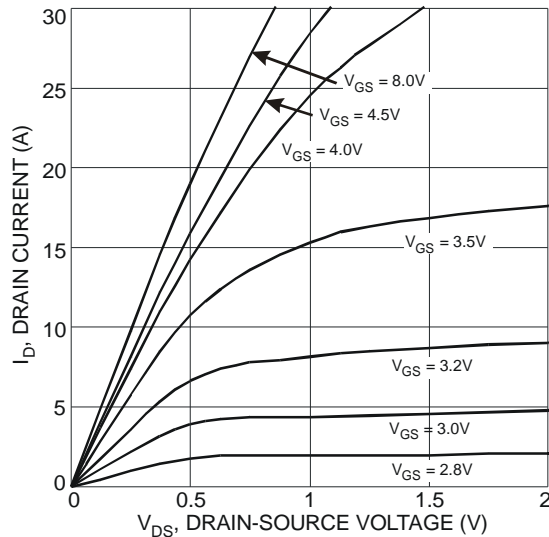


Fig. 1 Typical Output Characteristic

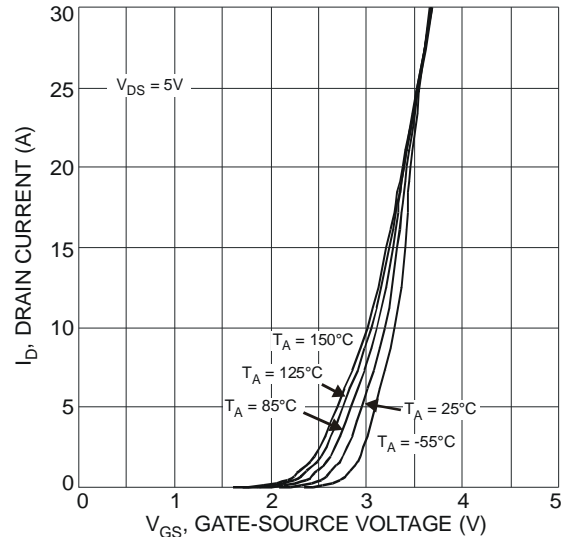


Fig. 2 Typical Transfer Characteristic

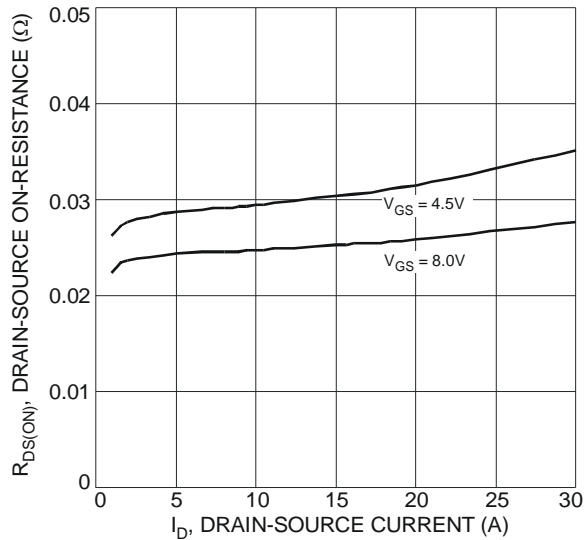


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

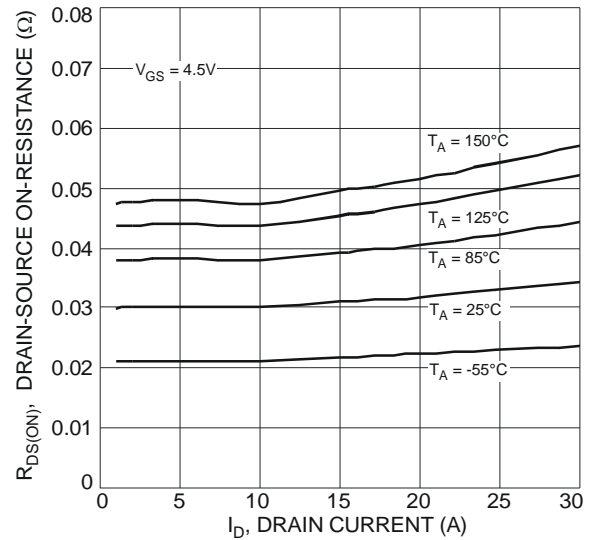


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

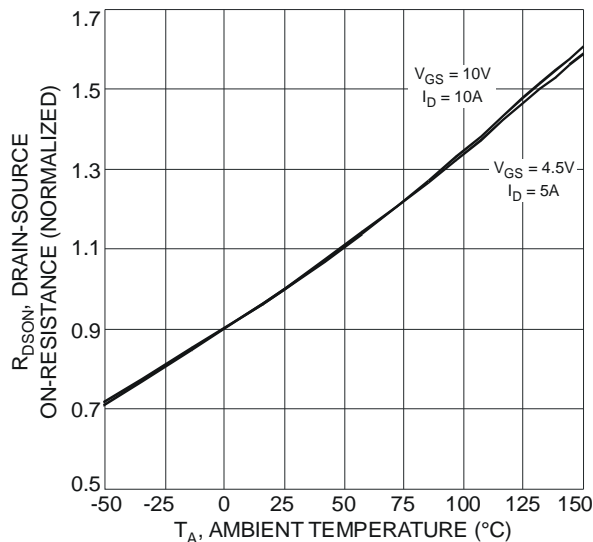


Fig. 5 On-Resistance Variation with Temperature

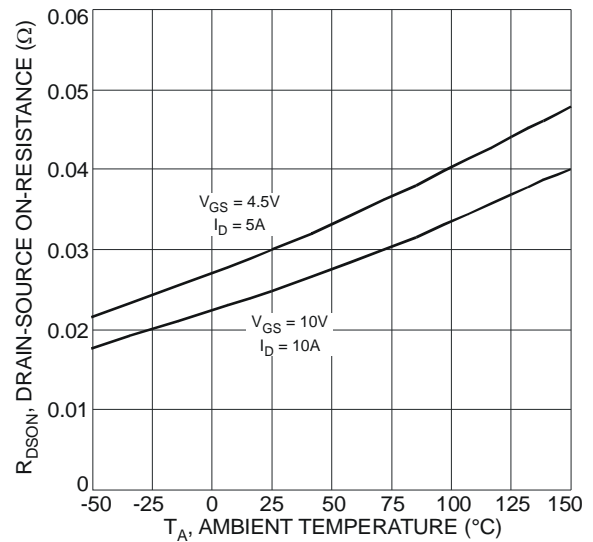


Fig. 6 On-Resistance Variation with Temperature

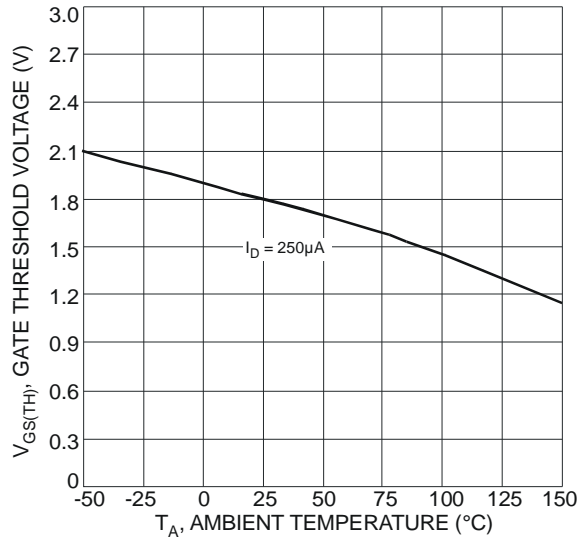


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

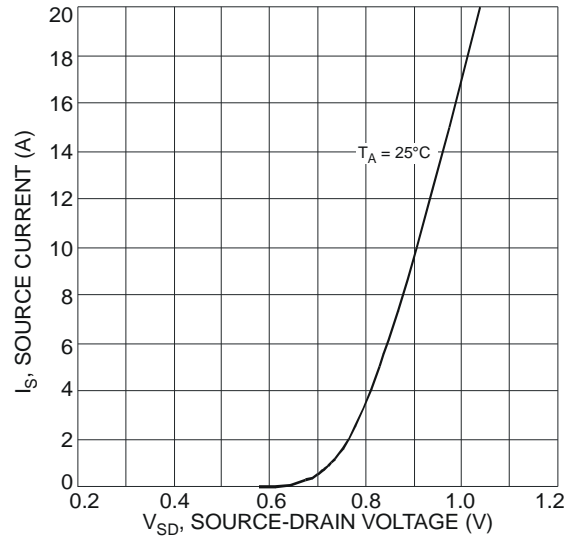


Fig. 8 Diode Forward Voltage vs. Current

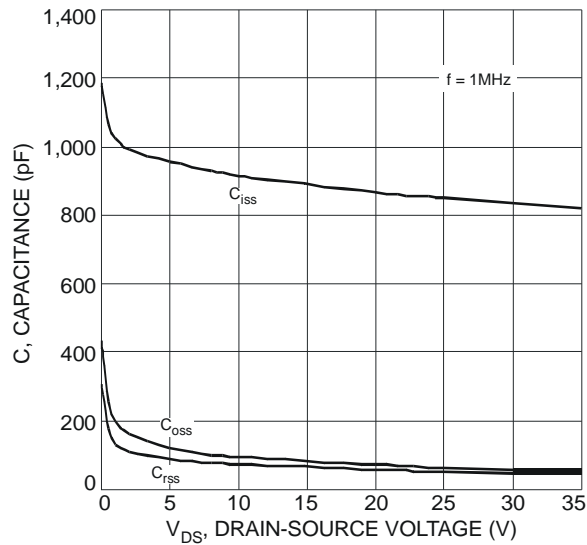


Fig. 9 Typical Total Capacitance

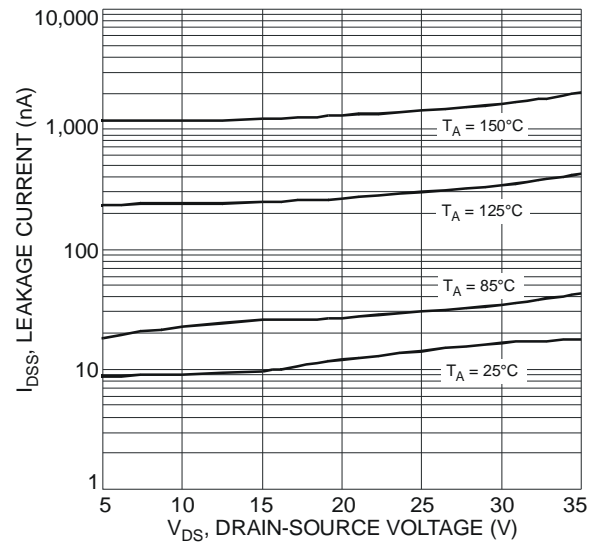


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

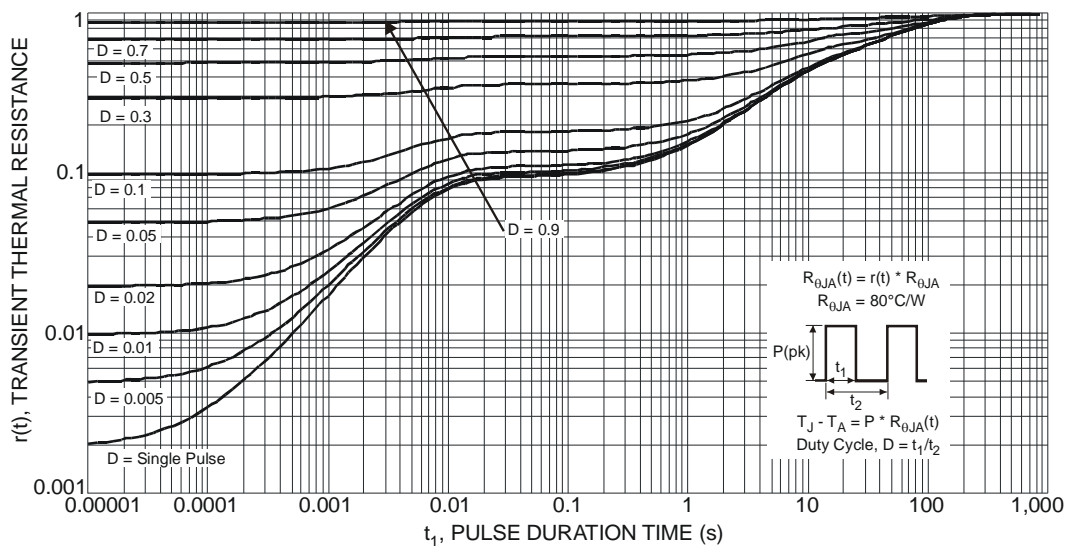


Fig. 11 Transient Thermal Response

P-CHANNEL, Q2

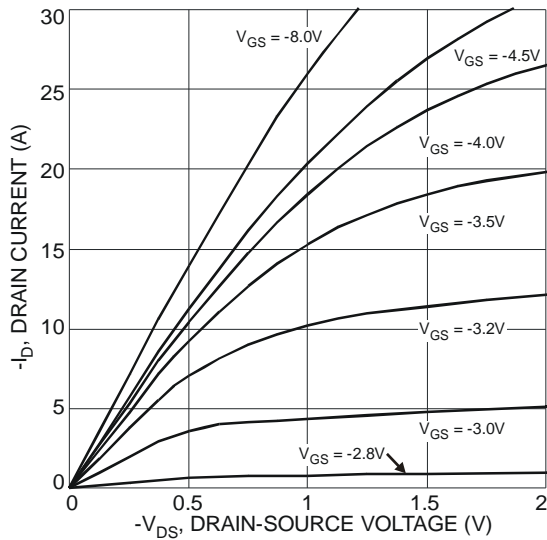


Fig. 12 Typical Output Characteristic

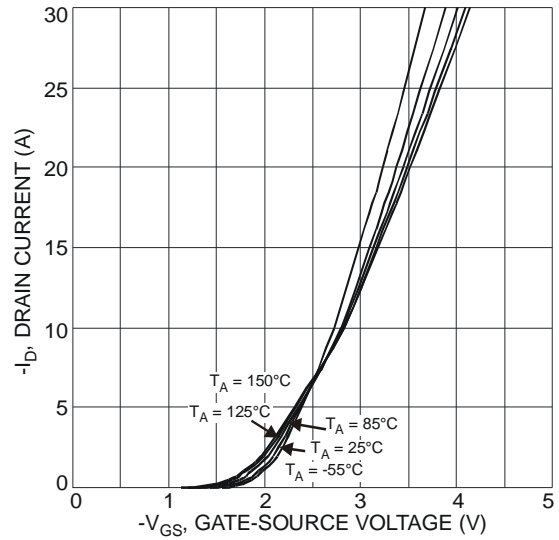


Fig. 13 Typical Transfer Characteristic

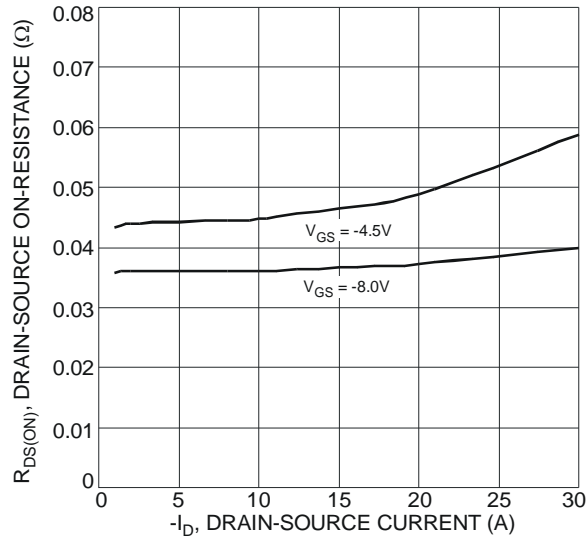


Fig. 14 Typical On-Resistance vs. Drain Current and Gate Voltage

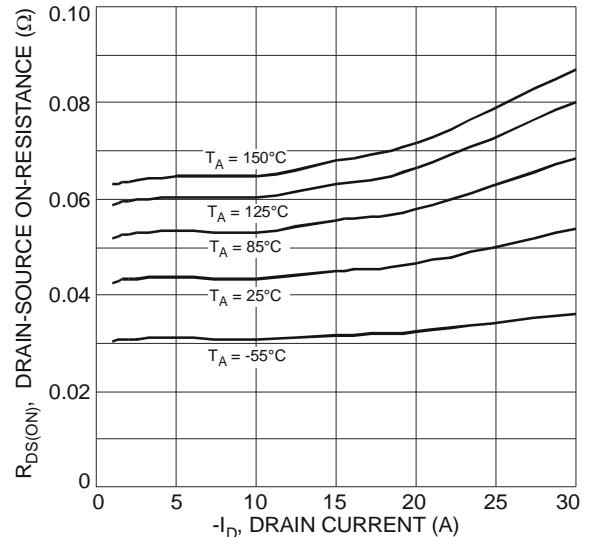


Fig. 15 Typical On-Resistance vs. Drain Current and Temperature

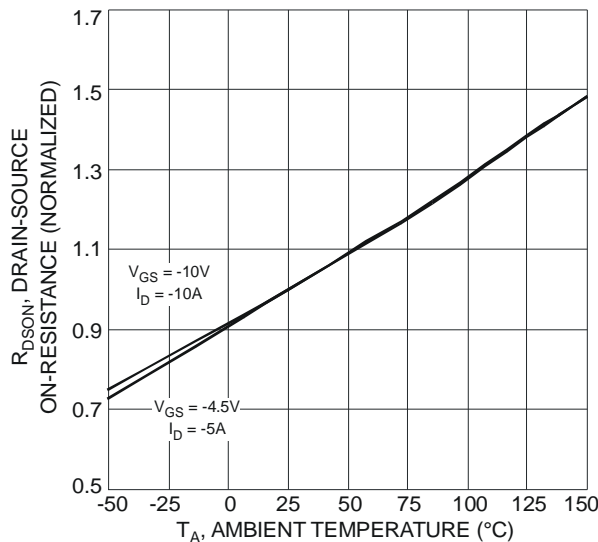


Fig. 16 On-Resistance Variation with Temperature

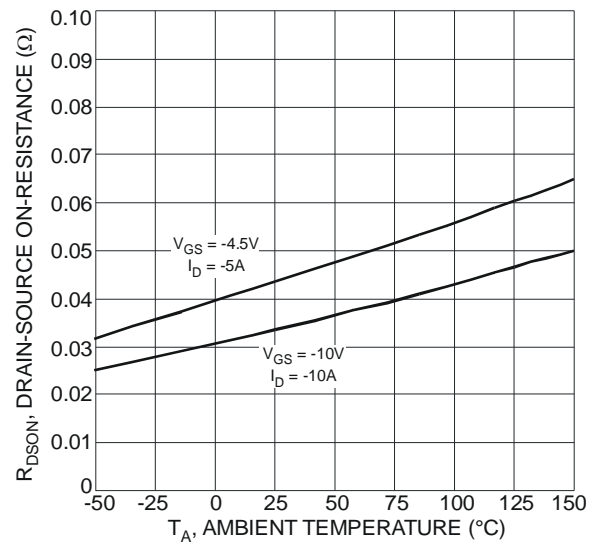


Fig. 17 On-Resistance Variation with Temperature

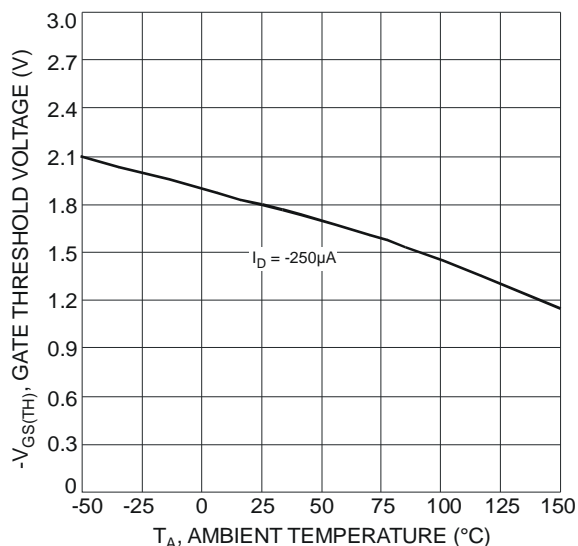


Fig. 18 Gate Threshold Variation vs. Ambient Temperature

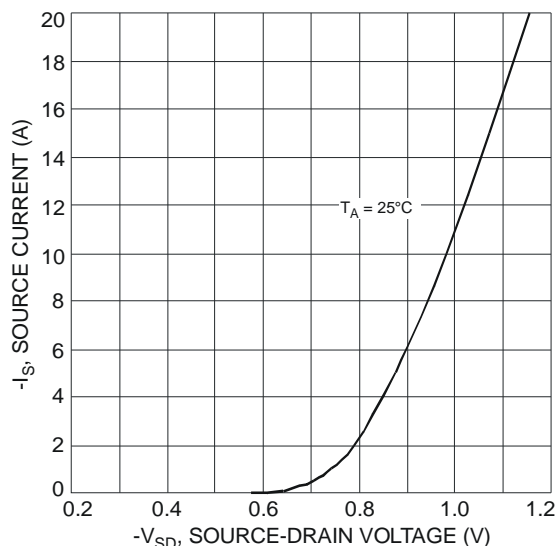


Fig. 19 Diode Forward Voltage vs. Current

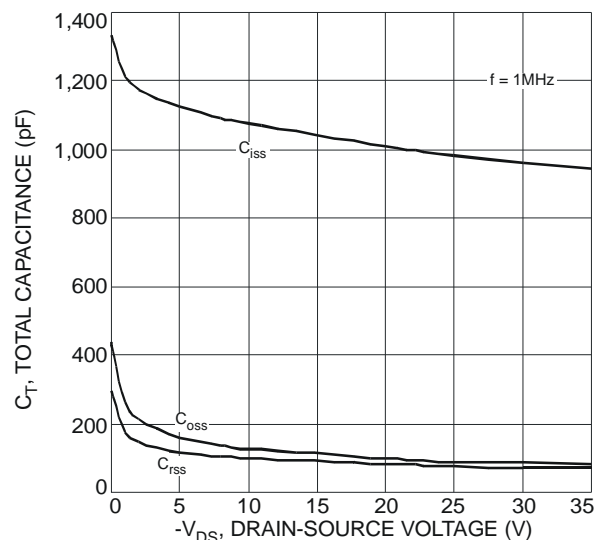


Fig. 20 Typical Total Capacitance

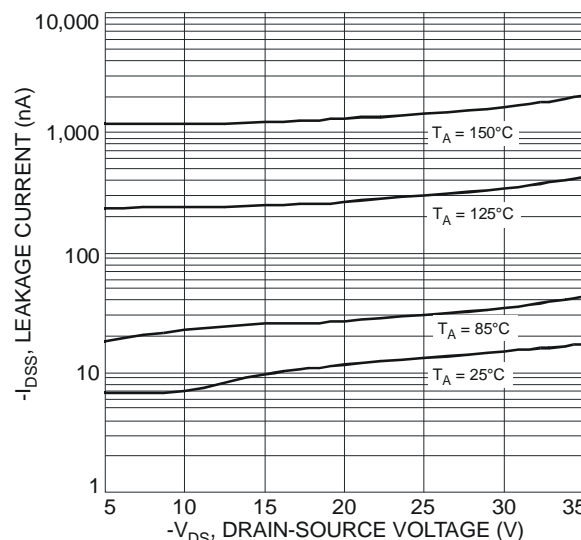


Fig. 21 Typical Leakage Current vs. Drain-Source Voltage

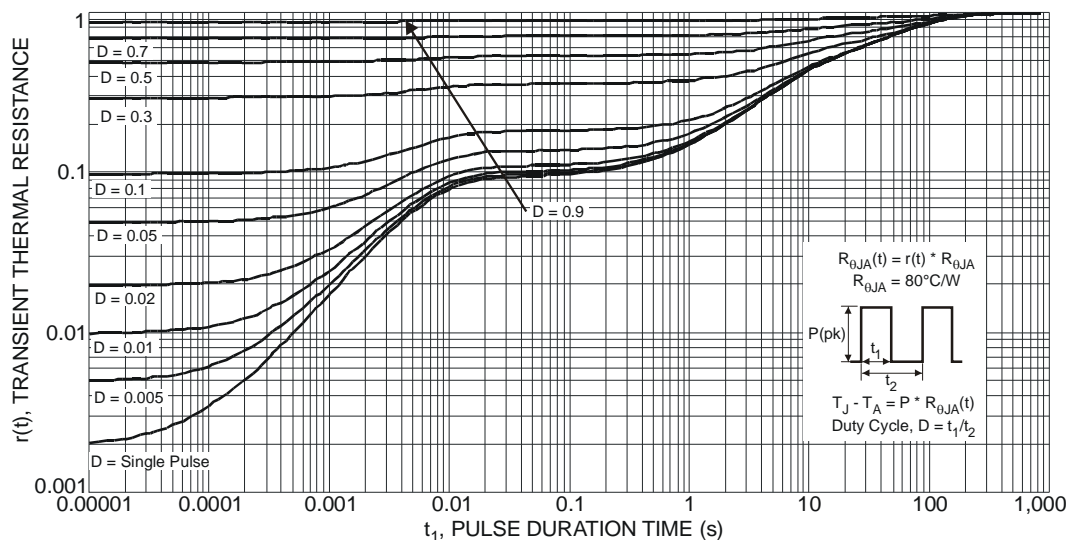
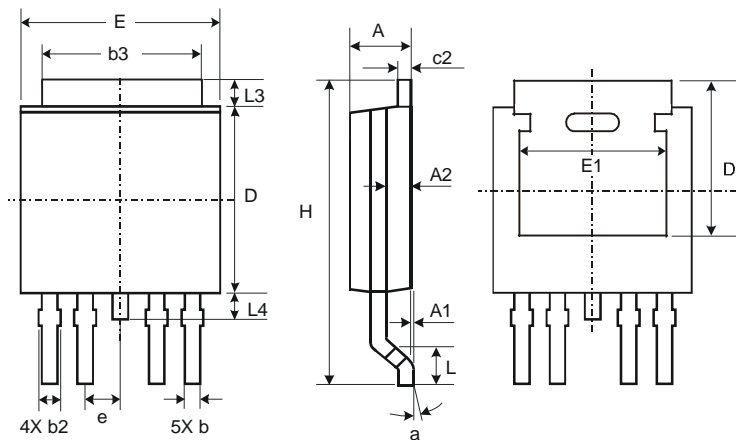


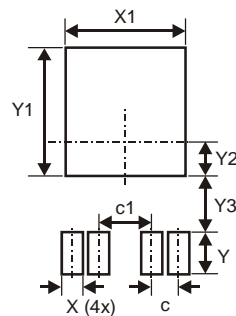
Fig. 22 Transient Thermal Response

Package Outline Dimensions



TO252-4L			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.51	0.71	0.583
b2	0.61	0.79	0.70
b3	5.21	5.46	5.33
c2	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	—	—
e	—	—	1.27
E	6.45	6.70	6.58
E1	4.32	—	—
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
c	1.27
c1	2.54
X	1.00
X1	5.73
Y	2.00
Y1	6.17
Y2	1.64
Y3	2.66

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